



**BSS127** 

### N-CHANNEL ENHANCEMENT MODE FIELD MOSFET

# **Product Summary**

BV <sub>DSS</sub>	R <sub>DS(ON)</sub>	Package	I <sub>D</sub> T <sub>A</sub> = +25°C
600V	160Ω @ V <sub>GS</sub> = 10V	SC59 SOT23	70mA

## **Description**

This new generation uses advanced planar technology MOSFET, provide excellent high voltage and fast switching, making it ideal for small-signal and level shift applications.

## **Applications**

- Motor Control
- Backlighting
- DC-DC Converters
- Power Management Functions

### **Features**

- Low Input Capacitance
- High BV<sub>DSS</sub> Rating for Power Application
- Low Input/Output Leakage
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- For automotive applications requiring specific change control (i.e.: parts qualified to AEC-Q101, PPAP capable, and manufactured in IATF 16949 certified facilities), please refer to the related automotive grade (Q-suffix) part. A listing can be found at

https://www.diodes.com/products/automotive/automotive-products/.

 This part is qualified to JEDEC standards (as references in AEC-Q101) for High Reliability.

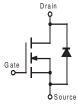
https://www.diodes.com/quality/product-definitions/

### **Mechanical Data**

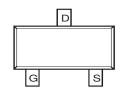
- Case: SC59 / SOT23
- Case Material: Molded Plastic "Green" Molding Compound.
   UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin Annealed over Copper Leadframe Solderable per MIL-STD-202, Method 208 (3)
- Terminal Connections: See Diagram
- Weight: 0.008 grams (Approximate)







Equivalent Circuit



Top View

### Ordering Information (Note 4)

Part Number	Case	Packaging
BSS127SSN-7	SC59	3000/Tape & Reel
BSS127S-7	SOT23	3000/Tape & Reel

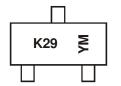
Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/



# **Marking Information**

SOT23



K29 = Product Type Marking Code YM = Date Code Marking

Y = Year (ex: D = 2016)M = Month (ex: 9 = September) **K28** 

SC59

K28 = Product Type Marking Code

YM = Date Code Marking Y = Year (ex: D = 2016)

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Date Code Key

 Jaio Oddo Hoj												
Year	201	3	2014		2015	20	016	2017		2018		2019
Code	Α		В		С		D	Е		F		G
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D

## **Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit		
Drain-Source Voltage			$V_{DSS}$	600	V
Gate-Source Voltage			V <sub>GSS</sub>	±20	V
Continuous Drain Current (Note 5) V <sub>GS</sub> = 10V	Steady State	$T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$	I <sub>D</sub>	50 40	mA
Continuous Drain Current (Note 6) V <sub>GS</sub> = 10V	Steady State	$T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$	I <sub>D</sub>	70 55	mA
Continuous Drain Current (Note 5) V <sub>GS</sub> = 5V	Steady State	$T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$	I <sub>D</sub>	45 35	mA
Continuous Drain Current (Note 6) V <sub>GS</sub> = 5V	Steady State	$T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$	I <sub>D</sub>	65 50	mA
Pulsed Drain Current @ T <sub>SP</sub> = +25°C (Note 7)	I <sub>DM</sub>	0.16	Α		

## **Thermal Characteristics**

Characteristic	Symbol	Value	Unit
Power Dissipation, @T <sub>A</sub> = +25°C (Note 5)	$P_{D}$	0.61	W
Thermal Resistance, Junction to Ambient @ T <sub>A</sub> = +25°C (Note 5)	$R_{\theta JA}$	204	°C/W
Power Dissipation, @T <sub>A</sub> = +25°C (Note 6)	$P_D$	1.25	W
Thermal Resistance, Junction to Ambient @ T <sub>A</sub> = +25°C (Note 6)	$R_{ heta JA}$	100	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C

Notes:

- Device mounted on FR-4 PCB with minimum recommended pad layout, single sided.
   Device mounted on 1" x 1" FR-4 PCB with high coverage 2 oz. Copper, single sided.
   Repetitive rating, pulse width limited by junction temperature, 10μs pulse, duty cycle = 1%.



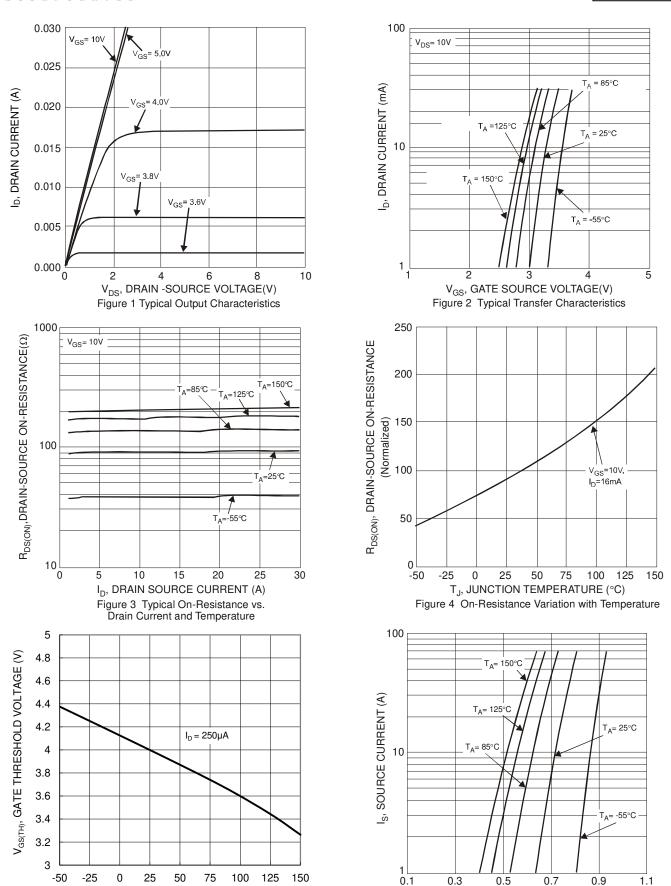
# Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 8)							
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	600	_	_	V	$V_{GS} = 0V, I_D = 250\mu A$	
Zero Gate Voltage Drain Current T <sub>J</sub> = +25°C	I <sub>DSS</sub>	_	_	0.1	μΑ	$V_{DS} = 600V, V_{GS} = 0V$	
Gate-Body Leakage	I <sub>GSS</sub>	_	_	±100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 8)							
Gate Threshold Voltage	V <sub>GS(TH)</sub>	3	_	4.5	V	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	
Static Drain-Source On-Resistance		_	80	160	Ω	$V_{GS} = 10V, I_D = 16mA$	
Static Drain-Source On-Nesistance	R <sub>DS(ON)</sub>	_	95	190	12	$V_{GS} = 5.0V, I_D = 16mA$	
Forward Transfer Admittance	Y <sub>fs</sub>	_	76	_	mS	$V_{DS} = 10V, I_D = 16mA$	
Diode Forward Voltage	V <sub>SD</sub>	_	_	1.5	V	V <sub>GS</sub> = 0V, I <sub>S</sub> = 16mA	
DYNAMIC CHARACTERISTICS (Note 9)							
Input Capacitance	C <sub>iss</sub>	_	21.8	_			
Output Capacitance	Coss	_	2.2	_	рF	$V_{DS} = 25V$ , $V_{GS} = 0V$ , $f = 1.0MHz$	
Reverse Transfer Capacitance	C <sub>rss</sub>	_	0.3	_			
Total Gate Charge	Qg	_	1.08	_		V 40V V 000V	
Gate-Source Charge	Q <sub>gs</sub>	_	0.08	_	nC	$V_{GS} = 10V, V_{DD} = 300V,$ $I_{D} = 0.01A$	
Gate-Drain Charge	$Q_{gd}$	_	0.50	_		ID = 0.01A	
Turn-On Delay Time	t <sub>D(ON)</sub>	_	5.0	_	ns	V <sub>DD</sub> = 300V, V <sub>GS</sub> = 10V,	
Turn-On Rise Time	t <sub>R</sub>	_	7.2	_	ns		
Turn-Off Delay Time	t <sub>D(OFF)</sub>	_	28.7	_	$R_{GEN} = 6\Omega,$ $R_{D} = 10$ mA		
Turn-Off Fall Time	t <sub>F</sub>	_	168	_	ns	TID = TOTTIA	
Reverse Recovery Time	t <sub>RR</sub>	_	131	_	ns	V <sub>B</sub> =300V, I <sub>F</sub> =0.016A,	
Reverse Recovery Charge	Q <sub>RR</sub>	_	32	_	nC	di/dt = 100A/μs	

Notes:

<sup>8.</sup> Short duration pulse test used to minimize self-heating effect. 9. Guaranteed by design. Not subject to production testing.





 $T_A$ , AMBIENT TEMPERATURE (°C)

Figure 5. Gate Threshold Variation vs. Ambient Temperature

 $V_{SD}$ , SOURCE-DRAIN VOLTAGE (V)

Figure 6 Diode Forward Voltage vs. Current



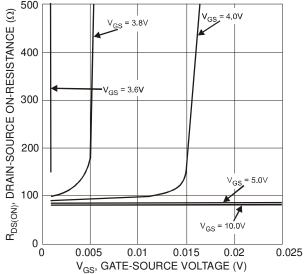


Figure 7 Typical On-Resistance vs. Drain Current and Gate Voltage

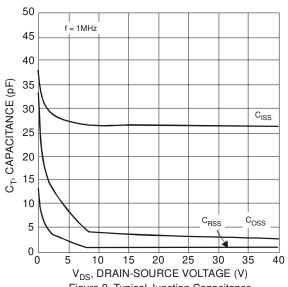
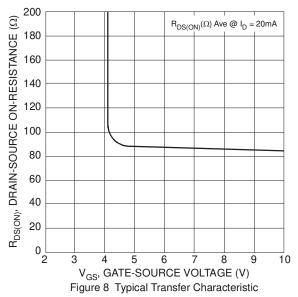
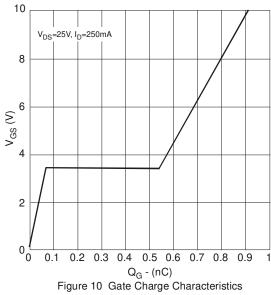


Figure 9 Typical Junction Capacitance





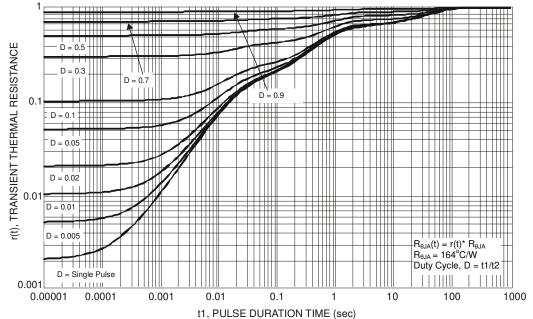


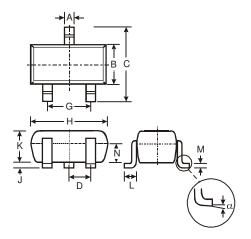
Figure 11 Transient Thermal Resistance



# **Package Outline Dimensions**

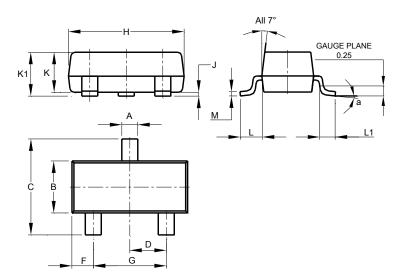
Please see http://www.diodes.com/package-outlines.html for the latest version.

### **SC59**



	SC59						
Dim	Min	Max	Тур				
Α	0.35	0.50	0.38				
В	1.50	1.70	1.60				
С	2.70	3.00	2.80				
D	-	-	0.95				
G	-	1	1.90				
Н	2.90	3.10	3.00				
J	0.013	0.10	0.05				
K	1.00	1.30	1.10				
L	0.35	0.55	0.40				
M	0.10	0.20	0.15				
N	0.70	0.80	0.75				
α	0°	8°	-				
All Dimensions in mm							

### SOT23

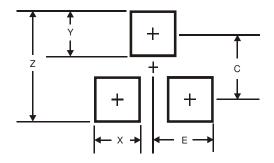


SOT23						
Dim	Min	Max	Тур			
Α	0.37	0.51	0.40			
В	1.20	1.40	1.30			
C	2.30	2.50	2.40			
D	0.89	1.03	0.915			
F	0.45	0.60	0.535			
G	1.78	2.05	1.83			
Н	2.80	3.00	2.90			
J	0.013	0.10	0.05			
K	0.890	1.00	0.975			
K1	0.903	1.10	1.025			
L	0.45	0.61	0.55			
L1	0.25	0.55	0.40			
М	0.085	0.150	0.110			
а	0°	8°				
All	All Dimensions in mm					

# **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.

### SC59



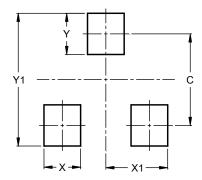
Dimensions	Value (in mm)
Z	3.4
Х	0.8
Υ	1.0
С	2.4
E	1.35



### Suggested Pad Layout (cont.)

Please see http://www.diodes.com/package-outlines.html for the latest version.

### SOT23



Dimensions	Value (in mm)
С	2.0
Х	0.8
X1	1.35
Υ	0.9
Y1	2.9

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